

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.51	100.0	0.86
			<b>Subtotal</b>	<b>0.51</b>	<b>100</b>	<b>0.86</b>
Wire	Impurity	Non hazardous		0	0.01	0
	Pure metal	Copper (Cu)	7440-50-8	0.41	99.99	0.7
			<b>Subtotal</b>	<b>0.41</b>	<b>100</b>	<b>0.7</b>
Die Attach	Hardener	Hardener		0.01	5.0	0.01
	Phenolic resin	Phenolic resin		0.01	5.0	0.01
	Epoxy resin	Epoxy resin system		0.01	5.0	0.01
	Lead alloy	Silver (Ag)	7440-22-4	0.12	85.0	0.2
			<b>Subtotal</b>	<b>0.15</b>	<b>100</b>	<b>0.23</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01	0.03	0.02
	Copper alloy	Zinc (Zn)	7440-66-6	0.06	0.15	0.1
	Copper alloy	Iron (Fe)	7439-89-6	0.88	2.29	1.49
	Copper alloy	Copper (Cu)	7440-50-8	37.22	96.97	63.19
	Copper alloy	Silver (Ag)	7440-22-4	0.21	0.56	0.36
			<b>Subtotal</b>	<b>38.38</b>	<b>100</b>	<b>65.16</b>
Mould Compound	Polymer	Epoxy Phenol Novolac resin (generic)	28064-14-4	2.06	3.5	3.49
	Filler	Silica -amorphous-	7631-86-9	4.7	8.0	7.98
	Filler	Silica fused	60676-86-0	46.99	80.0	79.76
	Carbon Black	Carbon black	1333-86-4	0.29	0.5	0.5
	Polymer	Epoxy resin system		4.7	8.0	7.98
			<b>Subtotal</b>	<b>58.74</b>	<b>100</b>	<b>99.71</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.83	100.0	3.1
			<b>Subtotal</b>	<b>1.83</b>	<b>100</b>	<b>3.1</b>
			<b>Total</b>	<b>100.02</b>	<b>100</b>	<b>169.76</b>

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